

PRINTED CIRCUIT BOARD AND ITS MANUFACTURE

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Abstract

PROBLEM TO BE SOLVED: To provide a printed circuit board provided with a conductor wiring layer, having high conductivity and superior anti-migration characteristic at low cost, and its manufacture.
SOLUTION: This printed circuit board has an insulation board containing at least an organic resin on the front side of which and/or inside of which a conductor wiring layer is formed, containing silver-coated copper powder that is coated with 1-30 wt.% of silver and whose average particle diameter is 3-10 μ m. In this case, a pulse current whose current density is 1-2000 A/cm² and whose pulse width is 0.01-1000 msec is applied to the conductor wiring layer, to form a neck part consisting of a silver-copper alloy to contact parts among the silver-coated copper powders 5, 5, and then thereby to enhance low resistance and anti-migration performance.

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